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10/06628  
02/06/02

U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10068628	02/06/2002	257	780	2844	2827

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Lee Jin-Hyuk;

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:  
REPUBLIC OF KOREA 01-8758 02/21/2001

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no  
Verified and Acknowledged Examiners's Initials

ATTORNEY DOCKET NO

9898-206

TITLE : Semiconductor device bonding pad resistant to stress and method of fabricating the same

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-96)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE		Total Claims	Print Claim for O.G.
Amount Due	Date Paid	DRAWING	
Primary Examiner		Sheets Drwg.	Figs. Drwg.
PREPARED FOR ISSUE		Print Fig.	
Application Examiner			
<input type="checkbox"/> TERMINAL DISCLAIMER			
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